MOSFET - N-Channel, SUPERFET® II, FRFET®

650 V, 54 A, 77 m Ω

FCH077N65F-F085

Description

SuperFET II MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently SuperFET II is very well suited for the Soft switching and Hard Switching topologies like High Voltage Full Bridge and Half Bridge DC-DC, Interleaved Boost PFC, Boost PFC for HEV-EV automotive.

SuperFET II FRFET MOSFET's optimized body diode reverse recovery performance can remove additional component and improve system reliability.

Features

- Typ. $R_{DS(on)} = 68 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 27 \text{ A}$
- Typ. $Q_{g(tot)} = 126 \text{ nC}$ at $V_{GS} = 10 \text{ V}$, $I_D = 27 \text{ A}$
- UIS Capability
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

Applications

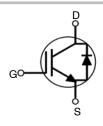
- Automotive On Board Charger
- Automotive DC/DC Converter for HEV



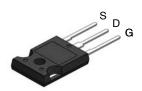
ON Semiconductor®

www.onsemi.com

V _{DS}	R _{DS(ON)} MAX	I _D MAX	
650 V	77 mΩ @ 10 V	54 A	

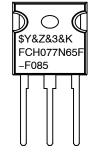


N-CHANNEL MOSFET



TO-247-3LD CASE 340CK

MARKING DIAGRAM



= ON Semiconductor Logo

\$Y

&Z = Assembly Plant Code &3 = Numeric Date Code

K = Lot Code

FCH077N65F-F085 = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Value	Unit
V _{DSS}	Drain to Source Voltage	650	V
V_{GSS}	Gate to Source Voltage	±20	V
I _D	Drain Current – Continuous (V _{GS} = 10) (Note 1)	54	А
	Pulsed Drain Current	See Fig. 4	Α
E _{AS}	Single Pulsed Avalanche Rating (Note 2)	1128	mJ
dv/dt	MOSFET dv/dt	100	V/ns
	Peak Diode Recovery dv/dt (Note 3)	50]
P_{D}	Power Dissipation	481	W
	Derate Above 25°C	3.85	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to + 150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Current is limited by bondwire configuration.
- 2. Starting $T_J = 25$ °C, L = 18.65 mH, $I_{AS} = 11$ A, $V_{DD} = 100$ V during inductor charging and $V_{DD} = 0$ V during time in avalanche. 3. $I_{SD} \le 27$ A, $di/dt \le 200$ A/µs, $V_{DD} \le 380$ V, starting $T_J = 25$ °C.

PACKAGE MARKING AND ORDERING INFORMATION

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FCH077N65F	FCH077N65F-F085	TO-247-3	-	-	30 Units

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max.	0.26	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max. (Note 4)	40	

^{4.} R_{0,JA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design, while $R_{\theta JA}$ is determined by the board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

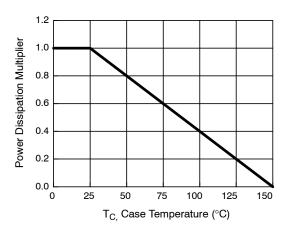
ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition		Min.	Тур.	Max.	Unit
OFF CHARA	ACTERISTICS					•	
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$		650	_	_	V
I _{DSS}	Drain to Source Leakage Current	V _{DS} = 650 V, V _{GS} = 0 V	T _J = 25 °C	-	-	10	μΑ
			T _J = 150 °C (Note 5)	-	-	1	mA
I _{GSS}	Gate to Source Leakage Current	V _{GS} = ±20 V		=	-	±100	nA
ON CHARA	CTERISTICS						
V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D =$	250 μΑ	3	-	5	V
R _{DS(on)}	Drain to Source On Resistance	I _D = 27 A	T _J = 25 °C	-	68	77	mΩ
		V _{GS} = 10 V	T _J = 150 °C (Note 5)	-	154	184	mΩ
YNAMIC C	HARACTERISTICS						
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS}	_S = 0 V,	-	5385	7162	pF
C _{oss}	Output Capacitance	f = 1 MHz V _{DS} = 0 V to 520 V, V _{GS} = 0 V f = 1 MHz		=	5629	7486	pF
C _{rss}	Reverse Transfer Capacitance			-	194	_	pF
C _{oss(eff.)}	Effective Output Capacitance			-	693	-	pF
Rg	Gate Resistance			-	0.5	-	Ω
Q _{g(tot)}	Total Gate Charge	$V_{DD} = 380 \text{ V}, I_{D}$	= 27 A _,	-	126	164	nC
Q _{g(th)}	Threshold Gate Charge	V _{GS} = 10 V	V _{GS} = 10 V		9	12	nC
Q _{gs}	Gate to Source Gate Charge			-	28	_	nC
Q_{gd}	Gate to Drain "Miller"Charge			=	53	-	nC
WITCHING	CHARACTERISTICS						
t _{on}	Turn-On Time	$V_{DD} = 380 \text{ V, } I_{D}$		-	64	148	ns
t _{d(on)}	Turn-On Delay Time	$V_{GS} = 10 \text{ V, R}_{G}$	= 4.7 \(\Omega \)	=	37	-	ns
t _r	Rise Time	1		-	27	_	ns
t _{d(off)}	Turn-Off Delay Time			-	105	_	ns
t _f	Fall Time			-	5.3	_	ns
t _{off}	Turn-Off Time			-	108.3	237	ns
RAIN-SOU	RCE DIODE CHARACTERISTICS						
V _{SD}	Source to Drain Diode Voltage	V _{GS} = 0 V, I _{SD} =	= 27 A	-	_	1.2	V
t _{rr}	Reverse Recovery Time	V _{DD} = 520 V, I _F	= 27 A,	-	190	-	ns
Q _{rr}	Reverse Recovery Charge	$di_{SD}/dt = 100 \text{ A}/\mu\text{s}$		_	1.5	_	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

5. The maximum value is specified by design at $T_J = 150^{\circ}$ C. Product is not tested to this condition in production.

TYPICAL CHARACTERISTICS



60 V_{GS} = 10V

V_{GS} = 10V

V_{GS} = 10V

V_{GS} = 10V

T_C, Case Temperature (°C)

Figure 1. Normalized Power Dissipation vs.

Case Temperature

Figure 2. Maximum Continuous Drain Current vs.

Case Temperature

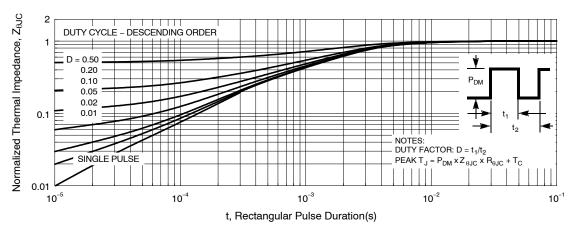


Figure 3. Normalized Maximum Transient Thermal Impedance

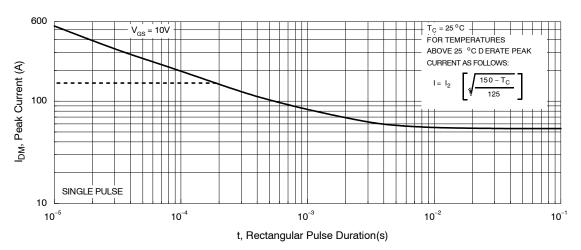


Figure 4. Peak Current Capability

TYPICAL CHARACTERISTICS

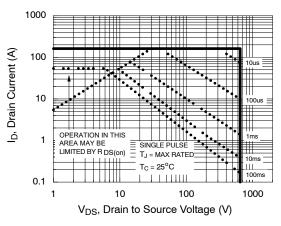


Figure 5. Forward Bias Safe Operating Area

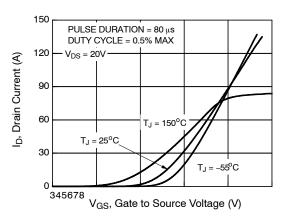


Figure 6. Transfer Characteristics

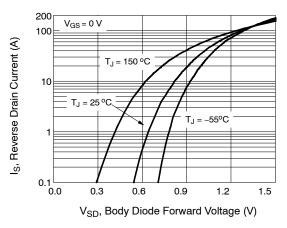


Figure 7. Forward Diode Characteristics

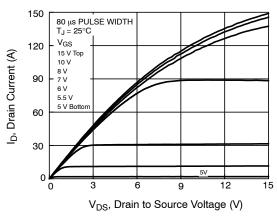


Figure 8. Saturation Characteristics

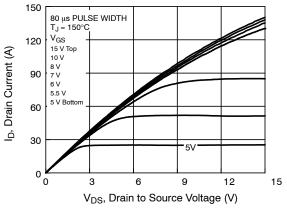


Figure 9. Saturation Characteristics

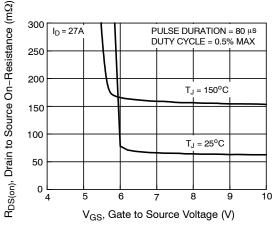


Figure 10. R_{DSON} vs. Gate Voltage

TYPICAL CHARACTERISTICS

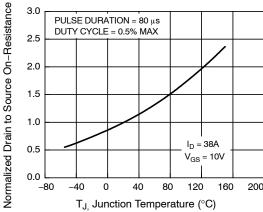


Figure 11. Normalized R_{DSON} vs. Junction Temperature



Figure 13. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

T_{J.} Junction Temperature (°C)

0 25 50

75

100 125 150

Normalized Drain to Source Breakdown Voltage

1.10

1.05

1.00

0.95

0.90

 $I_D = 10mA$

-50

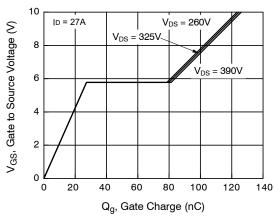


Figure 15. Gate Charge vs. Gate to Source Voltage

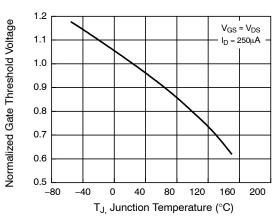


Figure 12. Normalized Gate Threshold Voltage vs. Temperature

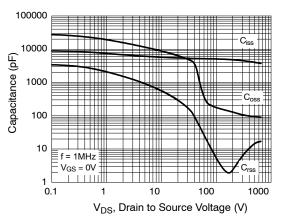


Figure 14. Capacitance vs. Drain to Source Voltage

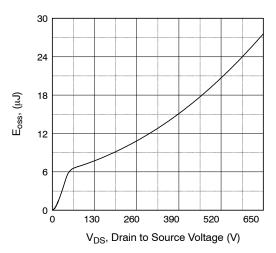


Figure 16. Eoss vs. Drain to Source Voltage

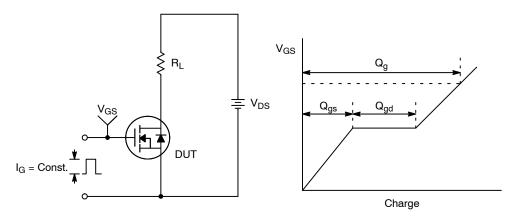


Figure 17. Gate Charge Test Circuit & Waveform

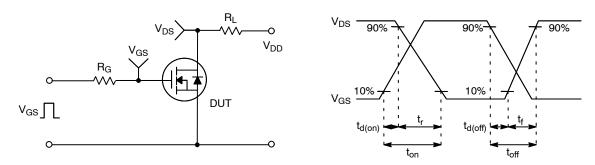


Figure 18. Resistive Switching Test Circuit & Waveforms

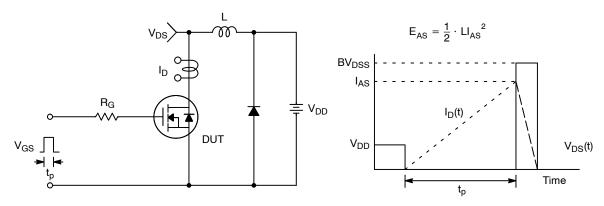


Figure 19. Unclamped Inductive Switching Test Circuit & Waveforms

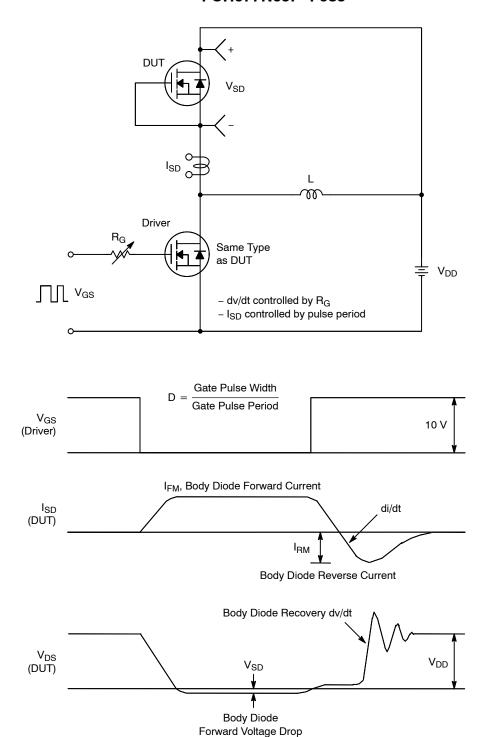


Figure 20. Peak Diode Recovery dv/dt Test Circuit & Waveforms

SUPERFET is a registered trademark of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries.

FRFET is a registered trademark of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries.

TO-247-3LD SHORT LEAD

CASE 340CK ISSUE A





- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code

A = Assembly Location

Y = Year

WW = Work Week

ZZ = Assembly Lot Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



DIM	MILLIMETERS			
DIIVI	MIN	NOM	MAX	
Α	4.58	4.70	4.82	
A 1	2.20	2.40	2.60	
A2	1.40	1.50	1.60	
b	1.17	1.26	1.35	
b2	1.53	1.65	1.77	
b4	2.42	2.54	2.66	
С	0.51	0.61	0.71	
D	20.32	20.57	20.82	
D1	13.08	~	~	
D2	0.51	0.93	1.35	
E	15.37	15.62	15.87	
E1	12.81	?	~	
E2	4.96	5.08	5.20	
е	~	5.56	~	
L	15.75	16.00	16.25	
L1	3.69	3.81	3.93	
ØΡ	3.51	3.58	3.65	
ØP1	6.60	6.80	7.00	
Q	5.34	5.46	5.58	
S	5.34	5.46	5.58	

DOCUMENT NUMBER:	98AON13851G	Electronic versions are uncontrolled except when accessed directly from the Document Report Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	TO-247-3LD SHORT LEAD		PAGE 1 OF 1	

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

ON Semiconductor and the are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor and see no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Email Requests to: orderlit@onsemi.com

ON Semiconductor Website: www.onsemi.com

TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800-282-9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative